

- 1 -

DATA PROCESSING APPARATUS FOR SEMICONDUCTOR  
PROCESSING APPARATUS

BACKGROUND OF THE INVENTION

The present invention relates to a data processing apparatus for a semiconductor manufacturing apparatus, and in particular, to a data processing  
5 apparatus for a semiconductor manufacturing apparatus suitable for a semiconductor manufacturing apparatus to conduct micromachining.

Fig. 12 shows a configuration of a data processing apparatus for a semiconductor manufacturing  
10 apparatus in the prior art. The configuration of Fig. 12 includes an etching system 1 of the semiconductor manufacturing apparatus, etching chambers 11 and 12 as processing chambers of the etching system 1, and sensors 13 and 14 respectively of the etching chambers  
15 11 and 12. Each of the sensors 13 and 14 measures various physical quantities, for example, a degree of vacuum in a vacuum chamber, plasma density, and an output from a ~~plasma~~ plasma emission spectrometer to produce sensor data. The configuration further  
20 includes a controller 15 of the etching system 1 to obtain wafer processing information items such as a type of a wafer being processed and a processing condition for the wafer. Reference numeral 2 indicates a data collector. Reference numeral 21 indicates a

data processor of the data collector 2. The data processor 21 collects the sensor data and the wafer processing information to store them in a database 22. Reference numeral 3 indicates a data analyzer which  
5 accesses the database (DB) 22 via the data processor 21 to acquire necessary data and analyzes the data. The operator of the semiconductor manufacturing apparatus can operate the semiconductor manufacturing apparatus according to results of the analysis.

10 Fig. 13 shows a sequence of processing executed by the data processor 21. As can be seen from Fig. 13, when the etching system 1 includes a plurality of etching chambers 11 and 12, the data processor 21 obtains, for example, alternately sensor data from the  
15 sensors 13 and 14 of the respective chambers 11 and 12 to store the data in the database 22.

#### SUMMARY OF THE INVENTION

Since the sensor data includes, for example, information with respect to time of a plasma emission  
20 spectrum (several thousand of data items per second) from the plasma emission spectrometer described above, a large amount of information items must be processed. Therefore, the data analyzer 3 takes a long period of time to obtain sensor data from the data collector 2  
25 and imposes at the same time a load onto the data collector 2. This hinders the data collecting operation of the data collector 2. Particularly, when the

when ~~the~~ etching system includes a plurality of etching chambers as shown in Fig. 12, the data collector must alternately handle the data items from the sensors in a duplicated manner as shown in Fig. 13. Therefore, it is difficult to guarantee a free period of time to be allocated for the data analyzer 3 to execute data processing, for example, a data extraction request. That is, in the data processing apparatus of the prior art, it is difficult to guarantee a wait period of time to execute processing such as analysis, and hence usability of the apparatus is deteriorated.

It is therefore an object of the present invention, which has been devised to remove the problem, to provide a data processing apparatus for a semiconductor manufacturing apparatus with high usability in which the wait time required for the processing is reduced.

To solve the problem, there is provided according to the present invention a data processing apparatus for a semiconductor manufacturing apparatus comprising a semiconductor manufacturing apparatus for executing processing for a wafer, a data collecting semiconductor device for collecting processing data generated in association with the processing, and a data copying semiconductor device for extracting the processing data collected in said data collecting semiconductor device and for producing a copy of the processing data. Moreover, the data processing

apparatus may comprise data analyzing means for analyzing the data copy produced by said data copying semiconductor device and for diagnosing a processing state of said processing apparatus.

5           Other objects, features and advantages of the invention will become apparent from the following description of the embodiments of the invention taken in conjunction with the accompanying drawings.

#### BRIEF DESCRIPTION OF THE DRAWINGS

10           Fig. 1 is a diagram showing a configuration of a data processing apparatus for a semiconductor manufacturing apparatus in an embodiment of the present invention;

15           Fig. 2 is a diagram for explaining data items stored in a database;

            Fig. 3 is a flowchart for explaining processing of a data processing apparatus for a semiconductor manufacturing apparatus;

20           Fig. 4 is a flowchart for explaining another processing of a data processing apparatus for a semiconductor processing apparatus;

            Fig. 5 is a diagram showing an example of an operation display screen presented on a display of a data copying semiconductor device;

25           Fig. 6 is a diagram showing another embodiment of the present invention;

            Fig. 7 is a diagram showing further another

embodiment of the present invention;

Fig. 8 is a diagram showing an example of an operation display screen presented on a display of a data copier;

5 Fig. 9 is a diagram showing still another embodiment of the present invention;

Fig. 10 is a diagram showing another embodiment of the present invention;

10 Fig. 11 is a diagram showing still another embodiment of the present invention;

Fig. 12 is a diagram showing a configuration of a data processing apparatus for a semiconductor manufacturing apparatus of the prior art; and

15 Fig. 13 is a diagram for explaining division of data processing.

#### DESCRIPTION OF THE EMBODIMENTS

Referring now to the accompanying drawings, description will be given of an embodiment of the present invention. Fig. 1 shows a configuration of a data processing apparatus for a semiconductor manufacturing apparatus in an embodiment of the present invention. The data processing apparatus shown in Fig. 1 includes a data copying semiconductor device 4a, a database copying semiconductor device 41, a database copy 42 produced by copying a database 22. In Fig. 1, the same constituent components as those of Fig. 12 are assigned with the same reference numeral and descrip-

tion thereof will be avoided.

As described above, the data processor 21 of the data collector 2 collects sensor data from the sensors 13 and 14 and wafer processing information from the controller 15 for each wafer to store the respective data in the database 22. The sensor data thus obtained for each wafer is stored as a sensor data file in the database 22. It is desirable that the sensor data for each wafer is related to the wafer processing data for the wafer using, for example, a list of correspondence therebetween.

The database copying semiconductor device 41 obtains the sensor data for each wafer, the wafer processing information for each wafer, and the list of correspondence therebetween to store these items in the database copy 42. The database copying semiconductor device 41 produces the copy during a free period of time of the data collector 2. When such a free period of time is insufficient, it is desirable that the processor 21 transfers the obtained sensor data to the copying device 4a at the end of each sensor data sampling period of time before the processor 21 registers the sensor data to the database 22. This reduces the data transfer time when compared with a case in which the data stored in the database 22 is read therefrom and is transferred to the copying semiconductor device 4a. When the quantity of sensor data varies between the sensors, for example, because only one of the etching

chambers is used, the data can be transferred to the copying semiconductor device 41 in a period of time in which the data collector 2 is operating with a lower load.

5                Since the copy of the wafer processing data including the sensor data for each wafer, the processing information for each wafer, and the correspondence list is stored in the database copy 42, the data analysis can be conducted without imposing any load  
10                onto the data collector 2. That is, the data analyzer 3 can access the database copy 42 without paying attention to the load imposed on the data collector 2.

                 Fig. 2 shows a configuration of data stored in the database 22. As can be seen from Fig. 2, the  
15                database 22 includes a sensor data file 221 in which the sensor data is filed for each wafer and a data management table 222 in which the wafer processing information and a correspondence list between the wafer processing information and the sensor data file are  
20                stored. The database copy 42 of the copy server 4a includes a sensor data file copy 421 and data management table copy 422 which are copies of part or all of the sensor data file 221 and the data management table 222, respectively. Since the sensor data has a large  
25                amount of data as described above, it is favorable to transfer the data to the copy server 4a in a free period of time of the data collector 2 or each time the data is received from each sensor. Since the size of

each record in the data management table 222 is small, it is favorable to transfer the data at a time when the wafer processing is terminated or when the processing of a lot is terminated.

5                    Fig. 3 is a flowchart to explain processing of the data processing apparatus for a semiconductor manufacturing apparatus according to the present embodiment. The flowchart includes part (a) "processing of the etching system 1", part (b) "processing of  
10 the data collector 2", and part (c) "processing of the data copying semiconductor device 4a".

                  First, in flowchart part (a) of the etching system 1, the system 1 starts wafer processing in step 11. In step 12, the controller 15 outputs wafer  
15 processing information such as a wafer processing recipe, a type of semiconductor chip on the wafer, a wafer number, and a processing lot number to the data collector 2. In step 13, the data collector 2 can acquire sensor data at a predetermined interval of time  
20 during the wafer processing. In step 14, a check is made to determine whether or not the wafer processing has been terminated. If the processing has been terminated, control goes to step 15 to wait for the wafer processing of a subsequent wafer.

25                    In flowchart part (b) of the data collector 2, whether or not the wafer processing information has been received from the etching system 1 is determined. If the information has been received, control goes to

15 X  
not in  
spec.



step 22. Otherwise, control goes to step 27. The collector 2 receives the sensor data in step 22 and then stores the data in the sensor data file 221 of the database 22. In step 24, the collector 2 determines  
5 whether or not the processing has been finished for the wafer. If the processing has been finished, the collector 2 updates the data management table 222 of the database 22 in step 25, and sends update information of the table 222 to the data copying semiconductor  
10 device 4a in step 26. In step 27, the collector 2 determines presence or absence of sensor data to be processed. If any sensor data remains for copy, the collector 2 sends the data to the copy server 4a.

In flowchart part (c) of the data copying  
15 semiconductor device 4a, the semiconductor device 4a waits for reception of data in step 31. When data of the data management table 222 is received, control goes to step 32, and then updates the data management table copy 422 in step 33. When sensor data is received,  
20 control goes to step 34, and then generates a sensor data file copy to store the file copy in the database copy 42.

Fig. 4 shows a flowchart of another processing in the data processing apparatus for a semiconductor manufacturing apparatus in which the data  
25 processor 21 generates data for the database 22 and simultaneously transfers the data to the copying semiconductor device 4a. The flowchart includes part

(a) "processing of the etching system 1", part (b)  
"processing of the data collector 2", and part (c)  
"processing of the data copying semiconductor device  
4a". In Fig. 4, the same constituent components as  
5 those of Fig. 3 are assigned with the same reference  
numeral and description thereof will be avoided.

In the case shown in Fig. 4, the data  
collector 2 stores the sensor data in the sensor data  
file 221 of the database 22 in step 23 and then  
10 transfers the sensor data to the copy server 4a in step  
23a. In this operation, the data can be transferred in  
a shorter period of time when compared with the case in  
which the data once stored in the database 22 is read  
therefrom and is then transferred to the copying  
15 semiconductor device 4a.

Fig. 5 shows an example of an operation  
display screen presented on a display of the data  
copying semiconductor device 4a. In an actual system,  
the data analyzer 3 analyzes a part of the data stored  
20 in the database 22. For example, the analyzer 3 may  
analyze only a semiconductor device having quite fine  
structure in some cases. In such a case, the user can  
specify the type of wafers to be analyzed. For example  
only a type of device or a type of recipe is copied so  
25 that a small amount of data is copied onto the database  
copy 42 in the copying device 4a, for example, only a  
semiconductor device type or a recipe type as the copy  
condition so that the data is copied onto the database

copy 42 of the copying semiconductor device 4a.

To specify the condition, the user inputs in a copy semiconductor device list display area 31 shown in Fig. 5 a list of semiconductor devices to be copied or the user inputs in a removal semiconductor device display area 32 a list of semiconductor devices to be excluded. Or, the user may specify or reserve a period of time to create a copy for the data collector 2.

This is advantageously effective, for example, when a large-capacity recording semiconductor device cannot be used for the database copy 42 of the copy server 4a or when data is obtained for a long period of time for the analysis.

Incidentally, when the copy condition is inputted, an authentication technique may be employed. For example, a password is inputted to protect the copy of the data. As a result, only particular information protected by the password can be stored in the database copy to thereby prevent leakage of the information.

Using the function, a semiconductor device maker of the system can limit a range of data to be presented to a vender of the apparatus. Alternatively, the apparatus vendor maker can limit a range of data to be presented to the semiconductor device maker.

Fig. 6 shows a configuration of another embodiment of the present invention. The configuration includes a data analyzer 3 disposed in a copying semiconductor device 4b. By including the data analyzer 3,

the copying semiconductor device 4b functions as a data analysis server. When the copying semiconductor device or the data analysis server is configured as a web application server, external input/output semiconductor  
5 devices 51 and 52 to be connected to the server can be easily implemented using a general web browser.

Fig. 7 shows a configuration of still another embodiment of the present invention. The configuration includes a data analyzer 3 and an input/output semi-  
10 conductor device 5 which are disposed in the copying semiconductor device 4c. The semiconductor device 4c is attached onto the data collector 2 such that the semiconductor device 4c can be removed from the collector 2 to be independently transported.

15 By constructing the copying semiconductor device 4c as a portable server or a portable analysis server, the semiconductor device 4c can be attached onto the data collector 2 so that data is analyzed according to necessity. That is, when the semicon-  
20 ductor device 4c is attached onto the data collector 2, the semiconductor device 4c can update the database copy 42 thereof for the analysis of data. Therefore, also when a client does not desire to install the data analyzer operating in a continuous fashion, it is  
25 possible to acquire data from the data collector 2.

This function is especially convenient when an engineer of the apparatus vendor visits the site for repair, maintenance, or process tuning. He is able to plug his

own copying device 4c into the data collector 2 so that the database copy 42 is synchronized with the original database 22.

Fig. 8 shows an example of the operation  
5 display screen of the copying semiconductor device 4c.

As described above, when the copying semiconductor device 4c is constructed as a portable server or a portable analysis server and is not continuously connected to the data collector 2, a large amount of  
10 data items not copied in the copying semiconductor device 4c remain in the data collector 2 depending on cases. In this situation, when the data collector 2 is connected to the copying semiconductor device 4c to start copying the data, the copying operation takes a  
15 long period of time and hence the analysis cannot be started. However, by specifying a condition of data items to be copied from the data collector 2 onto the data copying semiconductor device 4c before the copying is started, only the data necessary for the analysis  
20 can be copied. The condition of data items to be copied can be specified by, for example, a semiconductor device name formed on the wafer, a recipe name used for the wafer processing, or information of day and time of the processing as shown in Fig. 8.

Fig. 9 shows still another embodiment of the  
present invention. The configuration of Fig. 9 includes a realtime diagnosing semiconductor device 23 to diagnoses, for example, an end point of processing

of the etching system 1 in a realtime fashion. The device is embedded in the data collector 2 and high speed data exchange between the data processor 21 and the diagnosing device 23 is established. The configuration also includes a data analyzer 3 disposed in the data copying semiconductor device or an analysis server 4b. The analyzer 3 generates information necessary for the diagnosis in the diagnosing semiconductor device 23, for example, a determining criterion to determine the end point or a model formula for the diagnosis and then sends the information to the realtime diagnosing semiconductor device 23.

In the diagnosis using the data analyzer 3 of the data copying semiconductor device 4b, a long period of time is required before the diagnosis is started. Therefore, this operation is not suitable for the realtime diagnosis in some cases. However, by disposing the realtime diagnosing semiconductor device 23 in the data collector 2, the diagnosis can be immediately carried out.

Fig. 10 shows further another embodiment of the present invention. The configuration of Fig. 10 includes data collectors 2a and 2b and data analyzers 3a and 3b. As can be seen from the configuration, the etching system 1 includes a plurality of etching chambers 11 and 12. The data collector 2a and the data analyzer 3a are disposed for the etching chamber 11 and the data collector 2b and the data analyzer 3b are

disposed for the etching chamber 12.

By disposing a data collector and a data analyzer for each etching chamber, the data analyzer can transfer data from the data collector to the data  
5 analyzer using a free processing period of time between the continuous wafer processing of the etching chamber.

Fig. 11 shows still another embodiment of the present invention. The embodiment includes external databases 22a and 22b disposed at positions outside the  
10 data collector 2. The data collector 2 stores collected data in either one of the external storages 22a and 22b according to a storage change condition set by a data storage change condition setting semiconductor device 23. A storage change condition can be  
15 set from an external semiconductor device to the condition setting semiconductor device 23. The embodiment further includes a display 24 to display, for example, all storages or a storage being currently used.

20 The external storage may be a hard disk or a semiconductor memory. By connecting these external storage via, for example, a local area network (LAN) to the data analyzer, data can be obtained from the external storage not connected to the data collector 2  
25 to analyze the data without taking the load imposed on the data collector 2 into consideration.

The external storage may also include removable media such as a removable hard disk, a

removable digital video disk (DVD), a removable  
magneto-optical disk, and a zip drive (trademark) and so  
on. If the storage is constructed such that the body  
of media is ejected from the storage when the data  
5 collection is finished, the operator can easily collect  
the media. When such a removable media is employed as  
the external storage, the removable media can be  
incorporated into the data collector 2.

The storage change condition may be  
10 automatically set according to the capacity of the  
external storage. However, it is more convenient if  
the user can set the condition. The storage change  
condition may be specified by information of "day and  
time" or information for a periodic specification such  
15 as "Monday every week". Or, the condition may be a  
point of time when samples of a specified number of  
lots are completely processed. The storage where the  
data collector 21 is updating the database is called  
'active storage'. The operator can specify a storage  
20 change condition such that when the active storage is  
changed. After the storage change condition is  
fulfilled, the data collector 21 starts to store the  
database into another storage so that the storage for  
which the storing operation is finished is released  
25 from updating tasks. Thereafter, the operator may  
produce a backup copy of the database in the released  
storage. Or, if the storage is removable device, the  
operator can just pick up the removable media contain-



ing data. It is preferable that when the active storage is changed, the event is displayed on the storage display or a notification is sent to the operator via e-mail.

5           According to the embodiments described above, it is possible to provide a data processing apparatus for a semiconductor manufacturing apparatus with high usability in which the period of time required for the processing is reduced. Since a data collector and a  
10 data analyzer are disposed for each etching chamber in the processing chamber of the semiconductor manufacturing apparatus, the period of free time to be allocated to data processing such as a data extraction request of the data analyzer can be sufficiently  
15 guaranteed. Therefore, the load imposed on the data collector can be reduced. The data collector is connected to a plurality of external storages such that the storages are appropriately changed in the operation. This advantageously reduces the load imposed on  
20 the data collector, for example, for a data extraction request of the data analyzer. The collected data can be easily controlled.

          According to the present invention described above, it is possible to provide a data processing  
25 apparatus for a semiconductor manufacturing apparatus with high usability in which the period of time required for the processing is reduced.

It should be further understood by those

skilled in the art that the foregoing description has  
been made on embodiments of the invention and that  
various changes and modifications may be made in the  
invention without departing from the spirit of the  
5 invention and the scope of the appended claims.

11  
12  
13  
14  
15  
16  
17  
18  
19  
20  
21  
22  
23  
24  
25  
26  
27  
28  
29  
30  
31  
32  
33  
34  
35  
36  
37  
38  
39  
40  
41  
42  
43  
44  
45  
46  
47  
48  
49  
50  
51  
52  
53  
54  
55  
56  
57  
58  
59  
60  
61  
62  
63  
64  
65  
66  
67  
68  
69  
70  
71  
72  
73  
74  
75  
76  
77  
78  
79  
80  
81  
82  
83  
84  
85  
86  
87  
88  
89  
90  
91  
92  
93  
94  
95  
96  
97  
98  
99  
100  
101  
102  
103  
104  
105  
106  
107  
108  
109  
110  
111  
112  
113  
114  
115  
116  
117  
118  
119  
120  
121  
122  
123  
124  
125  
126  
127  
128  
129  
130  
131  
132  
133  
134  
135  
136  
137  
138  
139  
140  
141  
142  
143  
144  
145  
146  
147  
148  
149  
150  
151  
152  
153  
154  
155  
156  
157  
158  
159  
160  
161  
162  
163  
164  
165  
166  
167  
168  
169  
170  
171  
172  
173  
174  
175  
176  
177  
178  
179  
180  
181  
182  
183  
184  
185  
186  
187  
188  
189  
190  
191  
192  
193  
194  
195  
196  
197  
198  
199  
200  
201  
202  
203  
204  
205  
206  
207  
208  
209  
210  
211  
212  
213  
214  
215  
216  
217  
218  
219  
220  
221  
222  
223  
224  
225  
226  
227  
228  
229  
230  
231  
232  
233  
234  
235  
236  
237  
238  
239  
240  
241  
242  
243  
244  
245  
246  
247  
248  
249  
250  
251  
252  
253  
254  
255  
256  
257  
258  
259  
260  
261  
262  
263  
264  
265  
266  
267  
268  
269  
270  
271  
272  
273  
274  
275  
276  
277  
278  
279  
280  
281  
282  
283  
284  
285  
286  
287  
288  
289  
290  
291  
292  
293  
294  
295  
296  
297  
298  
299  
300  
301  
302  
303  
304  
305  
306  
307  
308  
309  
310  
311  
312  
313  
314  
315  
316  
317  
318  
319  
320  
321  
322  
323  
324  
325  
326  
327  
328  
329  
330  
331  
332  
333  
334  
335  
336  
337  
338  
339  
340  
341  
342  
343  
344  
345  
346  
347  
348  
349  
350  
351  
352  
353  
354  
355  
356  
357  
358  
359  
360  
361  
362  
363  
364  
365  
366  
367  
368  
369  
370  
371  
372  
373  
374  
375  
376  
377  
378  
379  
380  
381  
382  
383  
384  
385  
386  
387  
388  
389  
390  
391  
392  
393  
394  
395  
396  
397  
398  
399  
400  
401  
402  
403  
404  
405  
406  
407  
408  
409  
410  
411  
412  
413  
414  
415  
416  
417  
418  
419  
420  
421  
422  
423  
424  
425  
426  
427  
428  
429  
430  
431  
432  
433  
434  
435  
436  
437  
438  
439  
440  
441  
442  
443  
444  
445  
446  
447  
448  
449  
450  
451  
452  
453  
454  
455  
456  
457  
458  
459  
460  
461  
462  
463  
464  
465  
466  
467  
468  
469  
470  
471  
472  
473  
474  
475  
476  
477  
478  
479  
480  
481  
482  
483  
484  
485  
486  
487  
488  
489  
490  
491  
492  
493  
494  
495  
496  
497  
498  
499  
500  
501  
502  
503  
504  
505  
506  
507  
508  
509  
510  
511  
512  
513  
514  
515  
516  
517  
518  
519  
520  
521  
522  
523  
524  
525  
526  
527  
528  
529  
530  
531  
532  
533  
534  
535  
536  
537  
538  
539  
540  
541  
542  
543  
544  
545  
546  
547  
548  
549  
550  
551  
552  
553  
554  
555  
556  
557  
558  
559  
560  
561  
562  
563  
564  
565  
566  
567  
568  
569  
570  
571  
572  
573  
574  
575  
576  
577  
578  
579  
580  
581  
582  
583  
584  
585  
586  
587  
588  
589  
590  
591  
592  
593  
594  
595  
596  
597  
598  
599  
600  
601  
602  
603  
604  
605  
606  
607  
608  
609  
610  
611  
612  
613  
614  
615  
616  
617  
618  
619  
620  
621  
622  
623  
624  
625  
626  
627  
628  
629  
630  
631  
632  
633  
634  
635  
636  
637  
638  
639  
640  
641  
642  
643  
644  
645  
646  
647  
648  
649  
650  
651  
652  
653  
654  
655  
656  
657  
658  
659  
660  
661  
662  
663  
664  
665  
666  
667  
668  
669  
670  
671  
672  
673  
674  
675  
676  
677  
678  
679  
680  
681  
682  
683  
684  
685  
686  
687  
688  
689  
690  
691  
692  
693  
694  
695  
696  
697  
698  
699  
700  
701  
702  
703  
704  
705  
706  
707  
708  
709  
710  
711  
712  
713  
714  
715  
716  
717  
718  
719  
720  
721  
722  
723  
724  
725  
726  
727  
728  
729  
730  
731  
732  
733  
734  
735  
736  
737  
738  
739  
740  
741  
742  
743  
744  
745  
746  
747  
748  
749  
750  
751  
752  
753  
754  
755  
756  
757  
758  
759  
760  
761  
762  
763  
764  
765  
766  
767  
768  
769  
770  
771  
772  
773  
774  
775  
776  
777  
778  
779  
780  
781  
782  
783  
784  
785  
786  
787  
788  
789  
790  
791  
792  
793  
794  
795  
796  
797  
798  
799  
800  
801  
802  
803  
804  
805  
806  
807  
808  
809  
810  
811  
812  
813  
814  
815  
816  
817  
818  
819  
820  
821  
822  
823  
824  
825  
826  
827  
828  
829  
830  
831  
832  
833  
834  
835  
836  
837  
838  
839  
840  
841  
842  
843  
844  
845  
846  
847  
848  
849  
850  
851  
852  
853  
854  
855  
856  
857  
858  
859  
860  
861  
862  
863  
864  
865  
866  
867  
868  
869  
870  
871  
872  
873  
874  
875  
876  
877  
878  
879  
880  
881  
882  
883  
884  
885  
886  
887  
888  
889  
890  
891  
892  
893  
894  
895  
896  
897  
898  
899  
900  
901  
902  
903  
904  
905  
906  
907  
908  
909  
910  
911  
912  
913  
914  
915  
916  
917  
918  
919  
920  
921  
922  
923  
924  
925  
926  
927  
928  
929  
930  
931  
932  
933  
934  
935  
936  
937  
938  
939  
940  
941  
942  
943  
944  
945  
946  
947  
948  
949  
950  
951  
952  
953  
954  
955  
956  
957  
958  
959  
960  
961  
962  
963  
964  
965  
966  
967  
968  
969  
970  
971  
972  
973  
974  
975  
976  
977  
978  
979  
980  
981  
982  
983  
984  
985  
986  
987  
988  
989  
990  
991  
992  
993  
994  
995  
996  
997  
998  
999  
1000  
1001  
1002  
1003  
1004  
1005  
1006  
1007  
1008  
1009  
1010  
1011  
1012  
1013  
1014  
1015  
1016  
1017  
1018  
1019  
1020  
1021  
1022  
1023  
1024  
1025  
1026  
1027  
1028  
1029  
1030  
1031  
1032  
1033  
1034  
1035  
1036  
1037  
1038  
1039  
1040  
1041  
1042  
1043  
1044  
1045  
1046  
1047  
1048  
1049  
1050  
1051  
1052  
1053  
1054  
1055  
1056  
1057  
1058  
1059  
1060  
1061  
1062  
1063  
1064  
1065  
1066  
1067  
1068  
1069  
1070  
1071  
1072  
1073  
1074  
1075  
1076  
1077  
1078  
1079  
1080  
1081  
1082  
1083  
1084  
1085  
1086  
1087  
1088  
1089  
1090  
1091  
1092  
1093  
1094  
1095  
1096  
1097  
1098  
1099  
1100  
1101  
1102  
1103  
1104  
1105  
1106  
1107  
1108  
1109  
1110  
1111  
1112  
1113  
1114  
1115  
1116  
1117  
1118  
1119  
1120  
1121  
1122  
1123  
1124  
1125  
1126  
1127  
1128  
1129  
1130  
1131  
1132  
1133  
1134  
1135  
1136  
1137  
1138  
1139  
1140  
1141  
1142  
1143  
1144  
1145  
1146  
1147  
1148  
1149  
1150  
1151  
1152  
1153  
1154  
1155  
1156  
1157  
1158  
1159  
1160  
1161  
1162  
1163  
1164  
1165  
1166  
1167  
1168  
1169  
1170  
1171  
1172  
1173  
1174  
1175  
1176  
1177  
1178  
1179  
1180  
1181  
1182  
1183  
1184  
1185  
1186  
1187  
1188  
1189  
1190  
1191  
1192  
1193  
1194  
1195  
1196  
1197  
1198  
1199  
1200  
1201  
1202  
1203  
1204  
1205  
1206  
1207  
1208  
1209  
1210  
1211  
1212  
1213  
1214  
1215  
1216  
1217  
1218  
1219  
1220  
1221  
1222  
1223  
1224  
1225  
1226  
1227  
1228  
1229  
1230  
1231  
1232  
1233  
1234  
1235  
1236  
1237  
1238  
1239  
1240  
1241  
1242  
1243  
1244  
1245  
1246  
1247  
1248  
1249  
1250  
1251  
1252  
1253  
1254  
1255  
1256  
1257  
1258  
1259  
1260  
1261  
1262  
1263  
1264  
1265  
1266  
1267  
1268  
1269  
1270  
1271  
1272  
1273  
1274  
1275  
1276  
1277  
1278  
1279  
1280  
1281  
1282  
1283  
1284  
1285  
1286  
1287  
1288  
1289  
1290  
1291  
1292  
1293  
1294  
1295  
1296  
1297  
1298  
1299  
1300  
1301  
1302  
1303  
1304  
1305  
1306  
1307  
1308  
1309  
1310  
1311  
1312  
1313  
1314  
1315  
1316  
1317  
1318  
1319  
1320  
1321  
1322  
1323  
1324  
1325  
1326  
1327  
1328  
1329  
1330  
1331  
1332  
1333  
1334  
1335  
1336  
1337  
1338  
1339  
1340  
1341  
1342  
1343  
1344  
1345  
1346  
1347  
1348  
1349  
1350  
1351  
1352  
1353  
1354  
1355  
1356  
1357  
1358  
1359  
1360  
1361  
1362  
1363  
1364  
1365  
1366  
1367  
1368  
1369  
1370  
1371  
1372  
1373  
1374  
1375  
1376  
1377  
1378  
1379  
1380  
1381  
1382  
1383  
1384  
1385  
1386  
1387  
1388  
1389  
1390  
1391  
1392  
1393  
1394  
1395  
1396  
1397  
1398  
1399  
1400  
1401  
1402  
1403  
1404  
1405  
1406  
1407  
1408  
1409  
1410  
1411  
1412  
1413  
1414  
1415  
1416  
1417  
1418  
1419  
1420  
1421  
1422  
1423  
1424  
1425  
1426  
1427  
1428  
1429  
1430  
1431  
1432  
1433  
1434  
1435  
1436  
1437  
1438  
1439  
1440  
1441  
1442  
1443  
1444  
1445  
1446  
1447  
1448  
1449  
1450  
1451  
1452  
1453  
1454  
1455  
1456  
1457  
1458  
1459  
1460  
1461  
1462  
1463  
1464  
1465  
1466  
1467  
1468  
1469  
1470  
1471  
1472  
1473  
1474  
1475  
1476  
1477  
1478  
1479  
1480  
1481  
1482  
1483  
1484  
1485  
1486  
1487  
1488  
1489  
1490  
1491  
1492  
1493  
1494  
1495  
1496  
1497  
1498  
1499  
1500  
1501  
1502  
1503  
1504  
1505  
1506  
1507  
1508  
1509  
1510  
1511  
1512  
1513  
1514  
1515  
1516  
1517  
1518  
1519  
1520  
1521  
1522  
1523  
1524  
1525  
1526  
1527  
1528  
1529  
1530  
1531  
1532  
1533  
1534  
1535  
1536  
1537  
1538  
1539  
1540  
1541  
1542  
1543  
1544  
1545  
1546  
1547  
1548  
1549  
1550  
1551  
1552  
1553  
1554  
1555  
1556  
1557  
1558  
1559  
1560  
1561  
1562  
1563  
1564  
1565  
1566  
1567  
1568  
1569  
1570  
1571  
1572  
1573  
1574  
1575  
1576  
1577  
1578  
1579  
1580  
1581  
1582  
1583  
1584  
1585  
1586  
1587  
1588  
1589  
1590  
1591  
1592  
1593  
1594  
1595  
1596  
1597  
1598  
1599  
1600  
1601  
1602  
1603  
1604  
1605  
1606  
1607  
1608  
1609  
1610  
1611  
1612  
1613  
1614  
1615  
1616  
1617  
1618  
1619  
1620  
1621  
1622  
1623  
1624  
1625  
1626  
1627  
1628  
1629  
1630  
1631  
1632  
1633  
1634  
1635  
1636  
1637  
1638  
1639  
1640  
1641  
1642  
1643  
1644  
1645  
1646  
1647  
1648  
1649  
1650  
1651  
1652  
1653  
1654  
1655  
1656  
1657  
1658  
1659  
1660  
1661  
1662  
1663  
1664  
1665  
1666  
1667  
1668  
1669  
1670  
1671  
1672  
1673  
1674  
1675  
1676  
1677  
1678  
1679  
1680  
1681  
1682  
1683  
1684  
1685  
1686  
1687  
1688  
1689  
1690  
1691  
1692  
1693  
1694  
1695  
1696  
1697  
1698  
1699  
1700  
1701  
1702  
1703  
1704  
1705  
1706  
1707  
1708  
1709  
1710  
1711  
1712  
1713  
1714  
1715  
1716  
1717  
1718  
1719  
1720  
1721  
1722  
1723  
1724  
1725  
1726  
1727  
1728  
1729  
1730  
1731  
1732  
1733  
1734  
1735  
1736  
1737  
1738  
1739  
1740  
1741  
1742  
1743  
1744  
1745  
1746  
1747  
1748  
1749  
1750  
1751  
1752  
1753  
1754  
1755  
1756  
1757  
1758  
1759  
1760  
1761  
1762  
1763  
1764  
1765  
1766  
1767  
1768  
1769  
1770  
1771  
1772  
1773  
1774  
1775  
1776  
1777  
1778  
1779  
1780  
1781  
1782  
1783  
1784  
1785  
1786  
1787  
1788  
1789  
1790  
1791  
1792  
1793  
1794  
1795  
1796  
1797  
1798  
1799  
1800  
1801  
1802  
1803  
1804  
1805  
1806  
1807  
1808  
1809  
1810  
1811  
1812  
1813  
1814  
1815  
1816  
1817  
1818  
1819  
1820  
1821  
1822  
1823  
1824  
1825  
1826  
1827  
1828  
1829  
1830  
1831  
1832  
1833  
1834  
1835  
1836  
1837  
1838  
1839  
1840  
1841  
1842  
1843  
1844  
1845  
1846  
1847  
1848  
1849  
1850  
1851  
1852  
1853  
1854  
1855  
1856  
1857  
1858  
1859  
1860  
1861  
1862  
1863  
1864  
1865  
1866  
1867  
1868  
1869  
1870  
1871  
1872  
1873  
1874  
1875  
1876  
1877  
1878  
1879  
1880  
1881  
1882  
1883  
1884  
1885  
1886  
1887  
1888  
1889  
1890  
1891  
1892  
1893  
1894  
1895  
1896  
1897  
1898  
1899  
1900  
1901  
1902  
1903  
1904  
1905  
1906  
1907  
1908  
1909  
1910  
1911  
1912  
1913  
1914  
1915  
1916  
1917  
1918  
1919  
1920  
1921  
1922  
1923  
1924  
1925  
1926  
1927  
1928  
1929  
1930  
1931  
1932  
1933  
1934  
1935  
1936  
1937  
1938  
1939  
1940  
1941  
1942  
1943  
1944  
1945  
1946  
1947  
1948  
1949  
1950  
1951  
1952  
1953  
1954  
1955  
1956  
1957  
1958  
1959  
1960  
1961  
1962  
1963  
1964  
1965  
1966  
1967  
1968  
1969  
1970  
1971  
1972  
1973  
1974  
1975  
1976  
1977  
1978  
1979  
1980  
1981  
1982  
1983  
1984  
1985  
1986  
1987  
1988  
1989  
1990  
1991  
1992  
1993  
1994  
1995  
1996  
1997  
1998  
1999  
2000  
2001  
2002  
2003  
2004  
2005  
2006  
2007  
2008  
2009  
2010  
2011  
2012  
2013  
2014  
2015  
2016  
2017  
2018  
2019  
2020  
2021  
2022  
2023  
2024  
2025  
2026  
2027  
2028  
2029  
2030  
2031  
2032  
2033  
2034  
2035  
2036  
2037  
2038  
2039  
2040  
2041  
2042  
2043  
2044  
2045  
2046  
2047  
2048  
2049  
2050  
2051  
2052  
2053  
2054  
2055  
2056  
2057  
2058  
2059  
2060  
2061  
2062  
2063  
2064  
2065  
2066  
2067  
2068  
2069  
2070  
2071  
2072  
2073  
2074  
2075  
2076  
2077  
2078  
2079  
2080  
2081  
2082  
2083  
2084  
2085  
2086  
2087  
2088  
2089  
2090  
2091  
2092  
2093  
2094  
2095  
2096  
2097  
2098  
2099  
2100  
2101  
2102  
2103  
2104  
2105  
2106  
2107  
2108  
2109  
2110  
2111  
2112  
2113  
2114  
2115  
2116  
2117  
2118  
2119  
2120  
2121  
2122  
2123  
2124  
2125  
2126  
2127  
2128  
2129  
2130  
2131  
2132  
2133  
2134  
2135  
2136  
2137  
2138  
2139  
2140  
2141  
2142  
2143  
2144  
2145  
2146  
2147  
2148  
2149  
2150  
2151  
2152  
2153  
2154  
2155  
2156  
2157  
2158  
2159  
2160  
2161  
2162  
2163  
2164  
2165  
2166  
2167  
2168  
2169  
2170  
2171  
2172  
2173  
2174  
2175  
2176  
2177  
2178  
2179  
2180  
2181  
2182  
2183  
2184  
2185  
2186  
2187  
2188  
2189  
2190  
2191  
2192  
2193  
2194  
2195  
2196  
2197  
2198  
2199  
2200  
2201  
2202  
2203  
2204  
2205  
2206  
2207  
2208  
2209  
2210  
2211  
2212  
2213  
2214  
2215  
2216  
2217  
2218  
2219  
2220  
2221  
2222  
2223  
2224  
2225  
2226  
2227  
2228  
22